BG18A

5-4000 MHz Cascadable InGaP HBT Gain Block

Device Features

- OIP3 = 32.5 dBm @ 1900 MHz
- Gain = 15.1 dB @ 1900 MHz
- Output P1 dB = 18.9 dBm @ 1900 MHz
- 50 Ω Cascadable
- Patented temperature compensation
- Patented Over Voltage Protection Circuit
- Lead-free/RoHS-compliant SOT-89 SMT package

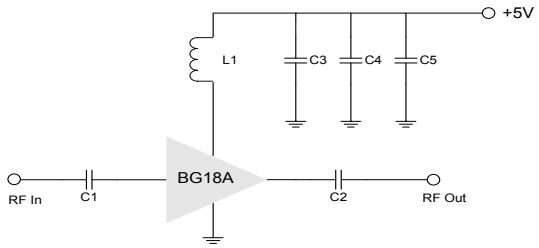
Product Description

BeRex's BG18A is a high performance InGaP/ GaAs HBT MMIC amplifier, internally matched to 50 Ohms and uses a patented ***temperature compensation*** circuit to provide stable current over the operating temperature range without the need for external components and a patented ***over voltage protection*** circuit to protect a internal device. The BG18A is designed for high linearity gain block applications that require excellent gain flatness. It is packaged in a RoHS-compliant with SOT-89 surface mount package.

Applications

- Base station Infrastructure/RFID
- Commercial/Industrial/Military wireless system

Applications Circuit



*C1, C2, C3 =100 pF ± 5%; C4 = 1000 pF ± 5%; C5 = 10uF; L1 = 33nH

*C1,C2 = 10nF; L1 = 2.2uH for IF Bandwidth

*Optimum value of L1 may vary with board design.

Typical Performance[1]

Parameter	Frequency					Unit
	500	900	1900	2140	2450	MHz
Gain	15.9	15.5	15.1	14.7	14.3	dB
S11	-11.3	-13.5	-13.1	-13.0	-13.1	dB
S22	-21.6	-19.9	-15.6	-15.2	-15.2	dB
OIP3[2]	37.5	36	32.5	31.5	30.5	dBm
P1dB	18.7	19.1	18.9	18.7	17.8	dBm
Noise Figure	4.2	4.2	4.2	4.2	4.4	dB

[1] Device performance _ measured on a BeRex evaluation board at 25°C, 50 Ω system.

[2] OIP3 _ measured with two tones at an output of 7 dBm per tone separated by 1 MHz.

	Min.	Typical	Max.	Unit
Bandwidth	5		4000	MHz
I_C @ (Vc = 5V)	60	70	80	mA
V_C		5.0		V
dG/dT		-0.004		dB/°C
R_{TH}		50		°C/W

Absolute Maximum Ratings

Parameter	Rating	Unit
Operating Case Temperature	-40 to +85	°C
Storage Temperature	-55 to +155	°C
Junction Temperature	+220	°C
Operating Voltage	+6.0	V
Supply Current	160	mA
Input RF Power	23	dBm

Operation of this device above any of these parameters may result in permanent damage.

Rev. D

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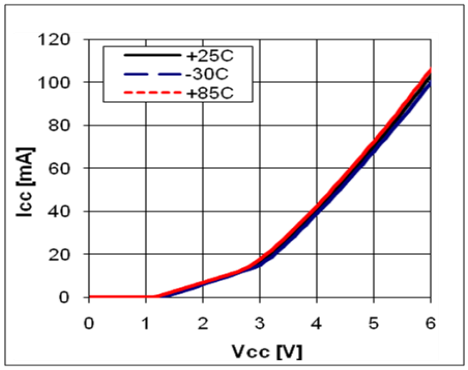
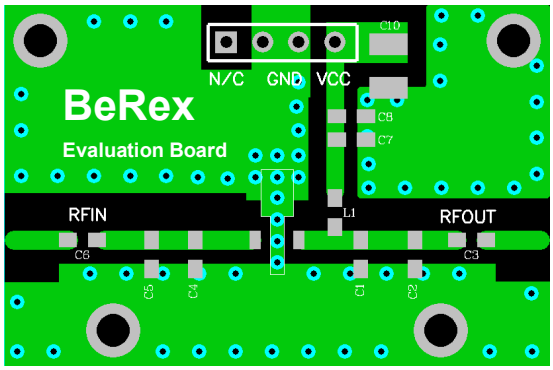
V-I Characteristics



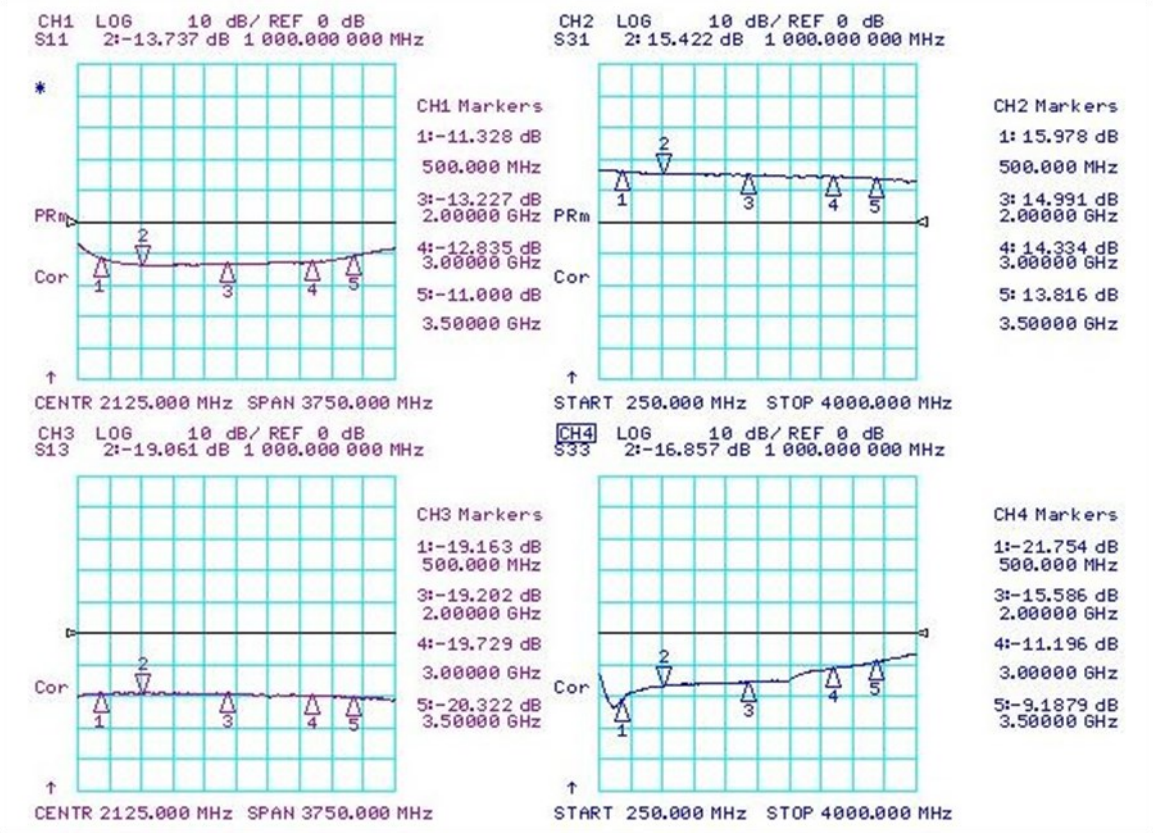
BeRex SOT89 Evaluation Board



*Dielectric constant _ 4.2 *RF pattern width 52mil *31mil thick FR4 PCB

Typical Device Data

S-parameters (Vc=5V, Ic=70mA, T=25°C)



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S-Parameter

(Vdevice = 5.0V, Icc = 70mA, T = 25 °C, calibrated to device leads)

Freq [MHz]	S11 [Mag]	S11 [Ang]	S21 [Mag]	S21 [Ang]	S12 [Mag]	S12 [Ang]	S22 [Mag]	S22 [Ang]
100	0.461	-166.4	9.317	162.1	0.071	13.3	0.396	-39.2
500	0.622	159.9	5.570	147.1	0.120	2.1	0.152	-138.9
1000	0.619	134.5	5.674	135.8	0.110	-9.4	0.138	127.5
1500	0.605	109.7	5.980	112.7	0.121	-15.8	0.233	78.0
2000	0.536	92.4	5.320	90.8	0.107	-32.1	0.307	42.3
2500	0.527	65.5	6.081	68.6	0.114	-32.3	0.379	16.6
3000	0.458	49.8	5.399	37.3	0.110	-51.4	0.433	-3.4
3500	0.469	22.8	4.547	19.3	0.098	-52.9	0.479	-31.5
4000	0.428	-4.2	4.219	-0.3	0.098	-66.0	0.558	-52.7

Typical Performance (Vd = 5V, Ic = 70mA, T = 25°C)

Freq	MHz	70	150	250	500	900	1900	2140	2450	3000
S21	dB	17.5	17.5	16.8	15.9	15.5	15.1	14.7	14.3	14.4
S11	dB	-17.0	-14.8	-16.4	-11.3	-13.5	-13.1	-13.0	-13.1	-12.7
S22	dB	-7.8	-9.2	-12.2	-21.6	-19.9	-15.6	-15.2	-15.2	-11.3
P1	dBm	18.1	18.7	18.6	18.7	19.1	18.9	18.7	17.8	17.1
OIP3	dBm	36.0	38.0	38.0	37.5	36	32.5	31.5	30.5	29
NF	dB	4.2	4.2	4.2	4.2	4.2	4.2	4.2	4.4	4.5

Typical Performance (Vd = 4.5V, Ic = 57mA, T = 25°C)

Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	17.3	15.9	15.4	14.9	14.6	14.2	13.5
S11	dB	-14	-18	-13	-13	-13	-12.8	-9.5
S22	dB	-7	-16	-17	-16	-15	-14	-7.7
P1	dBm	16.9	16.4	16.8	17.1	17.4	16.2	
OIP3	dBm	33.5	33	32.5	30.5	30.5	29	
NF	dB	4.4	4.4	4	4.2	4.3	4.5	

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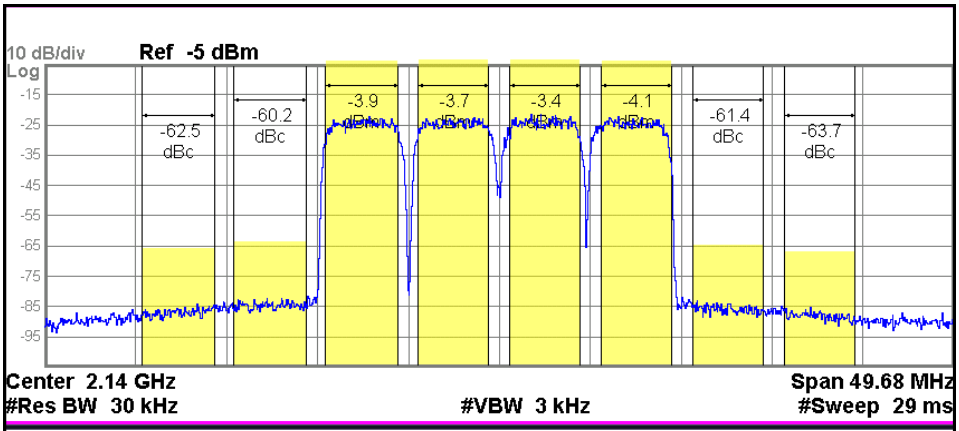
Typical Performance (Vd = 4V, Ic = 43mA, T = 25°C)

Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	17.7	15.7	15.2	14.8	14.4	14	13.3
S11	dB	-13	-18	-13	-13	-13	-13	-10
S22	dB	-7	-16	-18	-17	-16	-14.5	-7.8
P1	dBm	14.2	13.8	14.3	14.5	15.3	14.4	
OIP3	dBm	28	31	27.5	27	27	27.5	
NF	dB	4.2	4.2	3.9	4.2	4.2	4.3	

Typical Performance (Vd = 3.5V, Ic = 30mA, T = 25°C)

Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	17	15.1	14.7	14.3	14	13.6	12.9
S11	dB	-12	-18	-14	-14	-13.6	-13	-10
S22	dB	-6	-16	-22	-19	-18	-16	-8
P1	dBm	7.9	8.5	9	9.5	10.8	11.2	
OIP3	dBm	19.5	21	20.5	21	22.5	21.5	
NF	dB	4.2	4.2	3.8	3.9	4	4.2	

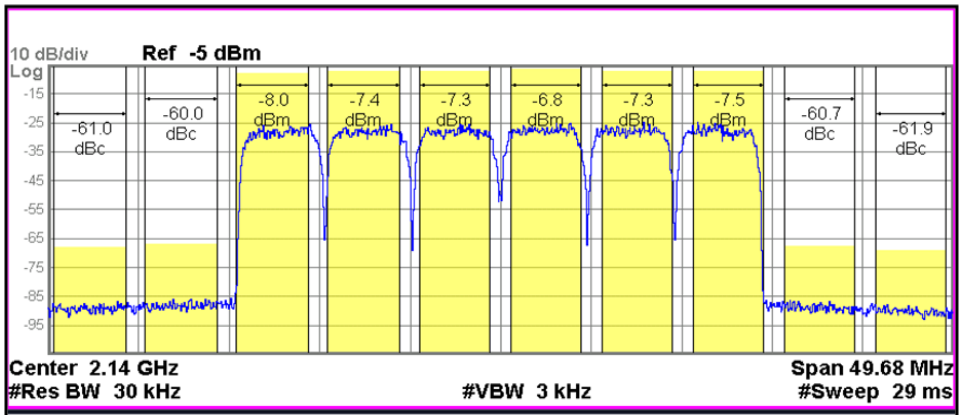
WCDMA 4FA 2140 -60dBc



Total Carrier Power 2.234 dBm/ 15.36 MHz ACP-IBW RRC Filter : On#

Carrier Power				Offset Freq	Integ BW	Lower dBc	Lower dBm	Upper dBc	Upper dBm
1	-3.921 dBm /	3.840 MHz		5.000 MHz	3.840 MHz	-60.19	-63.62	-61.36	-64.79
2	-3.736 dBm /	3.840 MHz		10.00 MHz	3.840 MHz	-62.52	-65.96	-63.74	-67.17
3	-3.432 dBm /	3.840 MHz							
4	-4.086 dBm /	3.840 MHz							

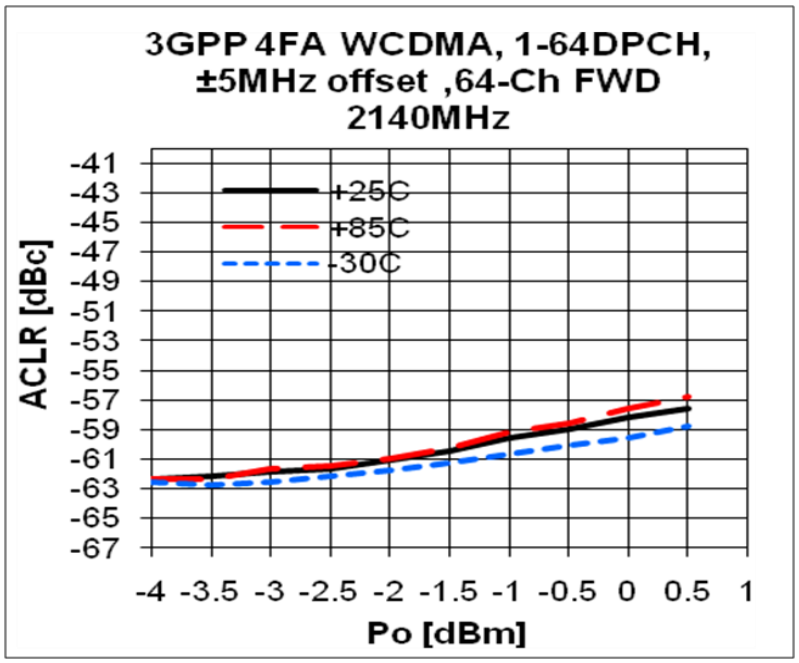
WCDMA 6FA 2140 -60dBc



Total Carrier Power 0.413 dBm/ 23.04 MHz ACP-IBW RRC Filter : On#

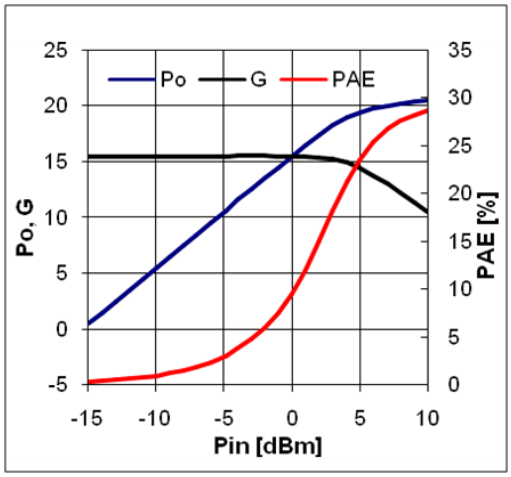
Carrier Power				Offset Freq	Integ BW	Lower dBc	Lower dBm	Upper dBc	Upper dBm
1	-7.997 dBm /	3.840 MHz		5.000 MHz	3.840 MHz	-59.98	-67.25	-60.67	-67.93
2	-7.407 dBm /	3.840 MHz		10.00 MHz	3.840 MHz	-60.98	-68.25	-61.94	-69.21
3	-7.333 dBm /	3.840 MHz							
4	-6.807 dBm /	3.840 MHz							
5	-7.263 dBm /	3.840 MHz							
6	-7.490 dBm /	3.840 MHz							

ACLR

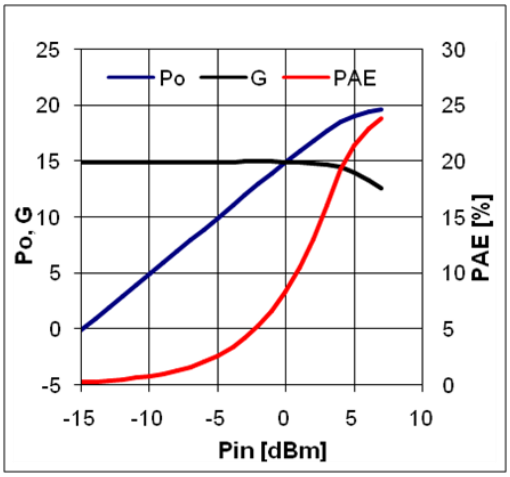


Device Performance

Pin-Pout-Gain

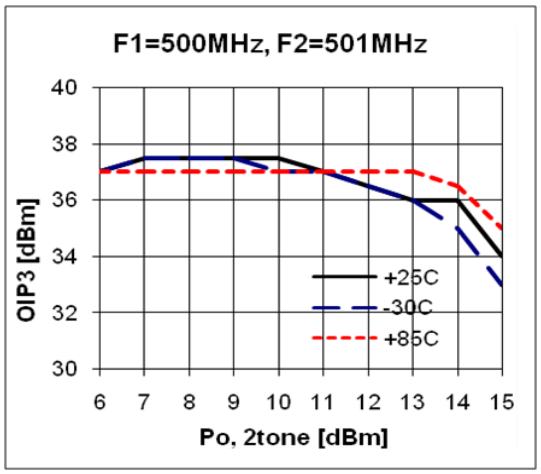


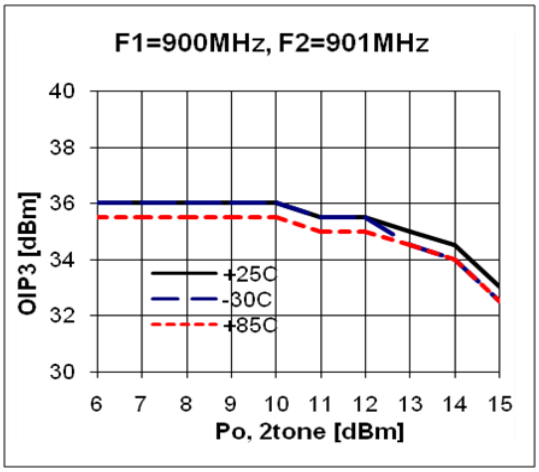
900MHz, 5V/73mA

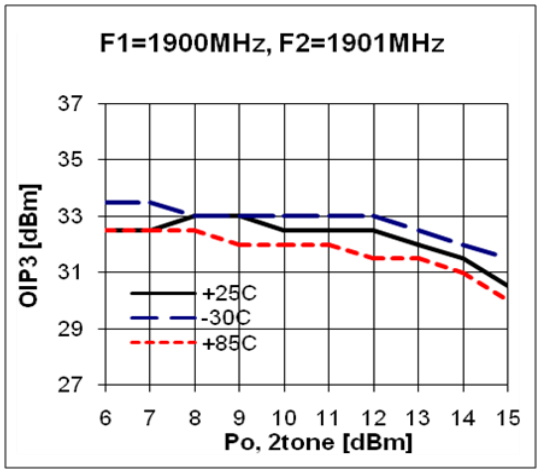


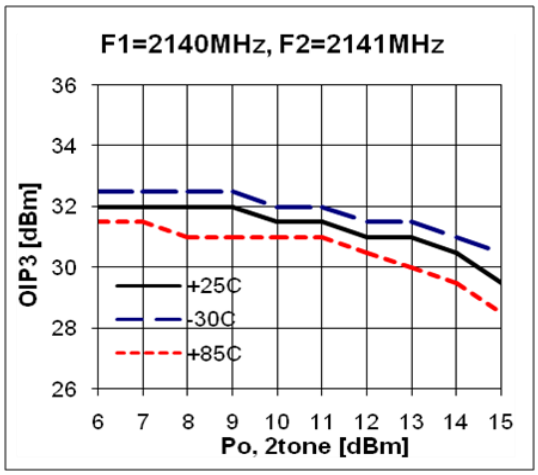
1900 MHz, 5V/73mA

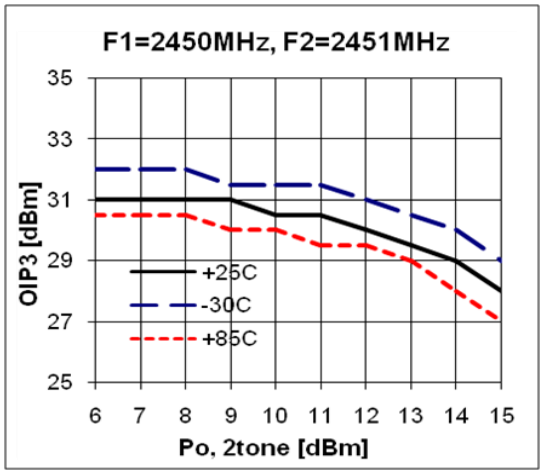
OIP3

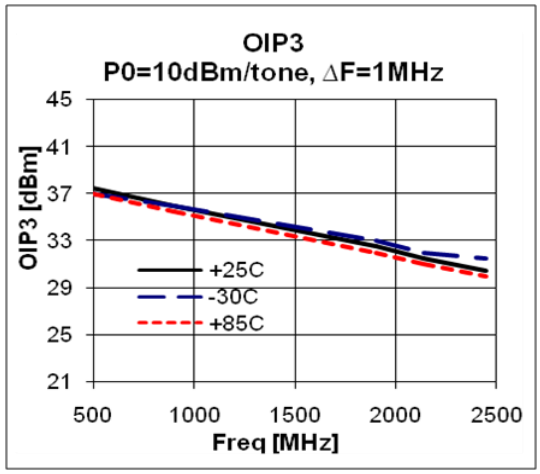




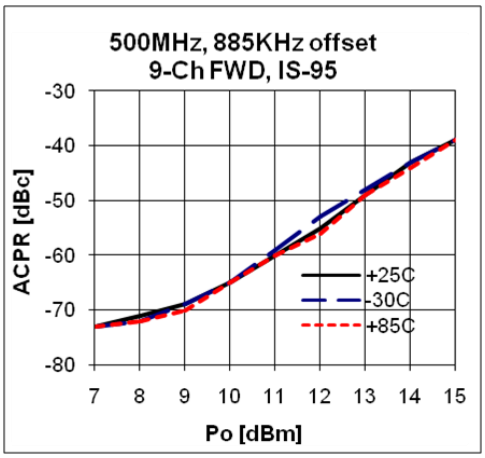


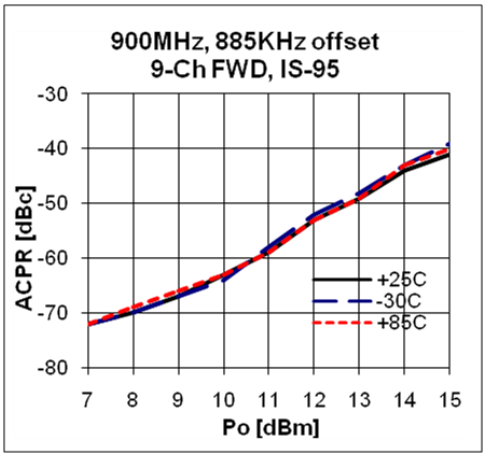


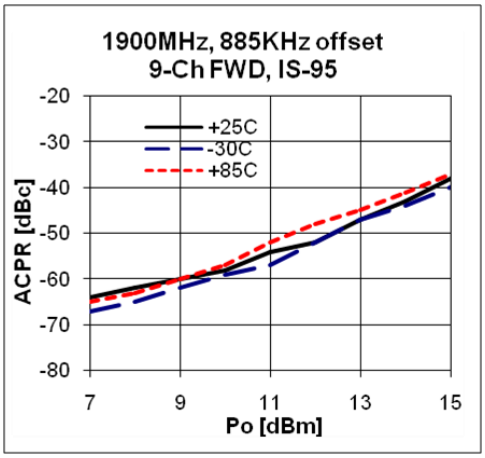


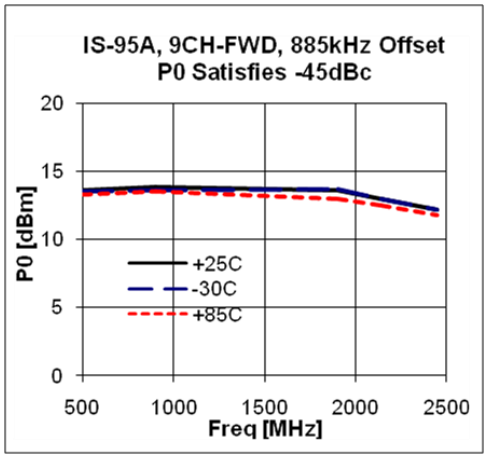


ACPR

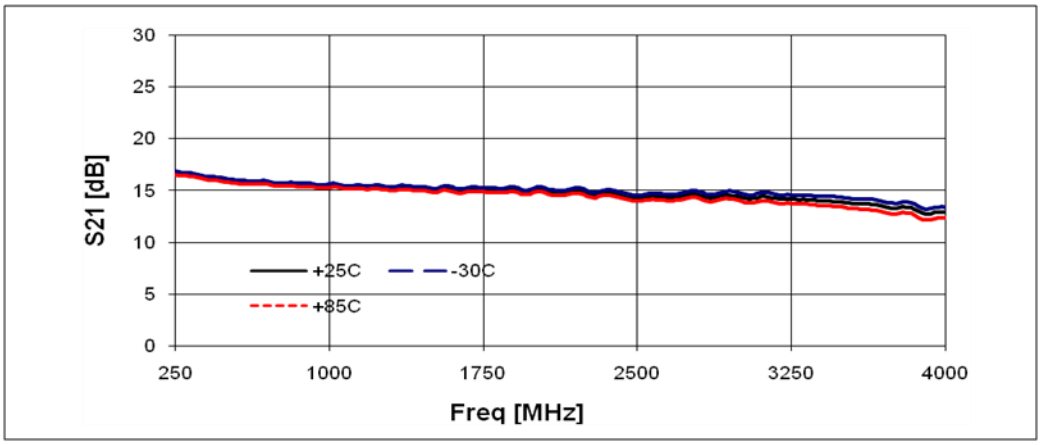








Gain Flatness



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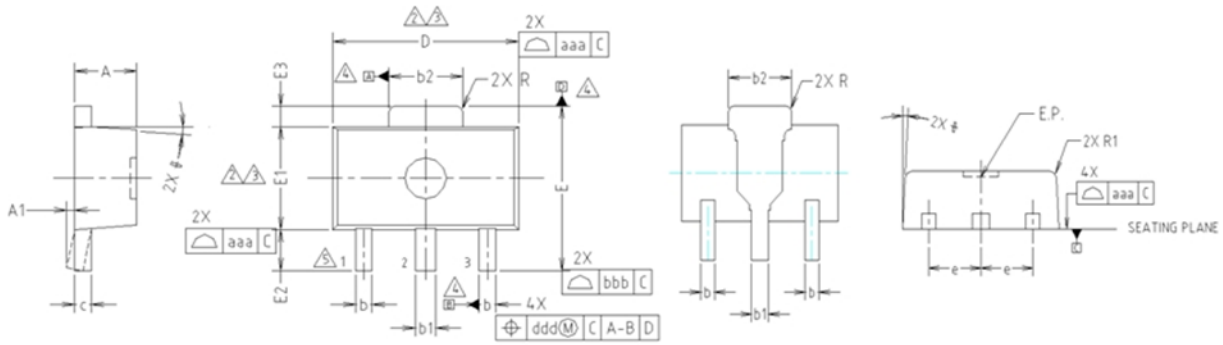
Package Outline Dimension



NOTE:

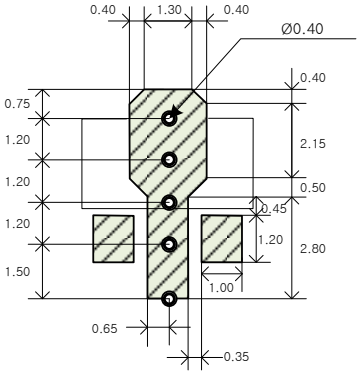
1. DIMENSIONS IN MILLIMETERS.
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.5mm PER END. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.5mm PER SIDE.
3. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
4. DATUMS A, B AND D TO BE DETERMINED 0.18mm FROM THE LEAD TIP.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

SYMBOL	MILLIMETERS			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	1.40	1.50	1.60	
A1	0.00	–	0.10	
b	0.38	0.42	0.48	
b1	0.48	0.52	0.58	
b2	1.79	1.82	1.87	
c	0.40	0.42	0.46	
D	4.40	4.50	4.70	2,3
E	3.70	4.00	4.30	
E1	2.40	2.50	2.70	2,3
E2	0.80	1.00	1.20	
E3	0.40	0.50	0.60	
e	1.50 TYP.			
θ	4° TYP.			
R	0.15 TYP.			
R1	–	–	0.20	

SYMBOL	TOLERANCES OF FORM AND POSITION	NOTE
aaa	0.15	
bbb	0.20	
ccc	0.10	
ddd	0.10	

Suggested PCB Land Pattern and PAD Layout

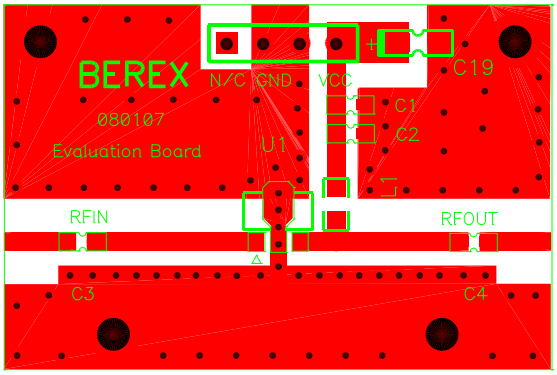
PCB Land Pattern



Note : All dimension _ millimeters

PCB lay out _ on BeRex website

PCB Mounting



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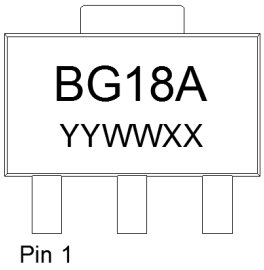
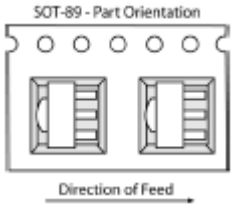
Package Marking



YY = Year, WW = Working Week,
XX = Wafer No.

Tape & Reel

SOT89



Packaging information:

Tape Width (mm): 12

Reel Size (inches): 7

Device Cavity Pitch (mm): 8

Devices Per Reel: 1000

Lead plating finish

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

MSL / ESD Rating

ESD Rating:	Class 1C
Value:	**Passes <2000V**
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114B
MSL Rating:	**Level 1 at +265°C convection reflow**
Standard:	JEDEC Standard J-STD-020

NATO CAGE code:

2	**N**	**9**	**6**	**F**